# 2.5Gbps, +3.3V Combined Transimpedance/Limiting Amplifier 

The MAX3866 combined transimpedance preamplifier and limiting postamplifier is intended for application in SDH/SONET systems operating at 2.488 Gbps . It operates from a single +3.3 V or +5 V supply and provides a differential output signal. The differential outputs are each $50 \Omega$ reverse terminated ( $100 \Omega$ differential termination) for low-noise and high-speed signal performance.
The small-signal bandwidth and noise performance is specified for a source capacitance of 0.5 pF . When the MAX3866 is used with the PIN photodetector, sensitivities better than $-22 d B m$ can be achieved. The MAX3866 is equipped with a programmable TL loss-of-power (LOP) output.

Applications
SDH/SONET Transmission Systems
PIN/Preamplifier Receivers
2.488Gbps ATM Receivers

Regenerators for SDH/SONET

Features
Input Sensitivities Better than $-22 \mathrm{dBm}(7.8 \mu \mathrm{Ap}-\mathrm{p})$
Overdrive Capability Better than +1.4 dBm
$\begin{aligned} & \text { (2.5mAp-p) }\end{aligned}$
$\begin{aligned} & \text { Single }+3.3 \mathrm{~V} \text { or }+5 \mathrm{~V} \text { Supply } \\ & \text { 165mW Power Dissipation (at } 3.3 \mathrm{~V} \text { ) } \\ & \text { 1.8GHz Analog Input Bandwidth }\end{aligned}$

- Programmable Loss-of-Power Indicator
- 100 $\Omega$ Differential Output

Ordering Information

| PART | TEMP. RANGE | PIN-PACKAGE |
| :---: | :---: | :--- |
| MAX3866E/D | (see Note) | Dice |

Note: Dice are designed to operate over a $-40^{\circ} \mathrm{C}$ to $+120^{\circ} \mathrm{C}$ junction temperature ( $T_{j}$ ) range, but are tested and guaranteed at $T_{A}=+25^{\circ} \mathrm{C}$.

## Pad Configuration appears at end of data sheet.

Typical Application Circuit


# 2.5Gbps, +3.3V Combined Transimpedance/Limiting Amplifier 

## ABSOLUTE MAXIMUM RATINGS

VCCD Voltage $\qquad$ VCCS Voltage $\qquad$ $0 \leq$ VCCS $\leq$ VCCD and if VCCD $\geq 3.13 \mathrm{~V}$ then $3.13 \mathrm{~V} \leq \mathrm{VCCS} \leq \mathrm{VCCD}$
CHF+, CHF-, FIL, INV, LOP Voltage .......-0.5V to (VCCD + 0.5V)
IN-, IN+ Voltage $\qquad$ ge. $\qquad$ (VCCD - 1.6 V ) to (VCCD +0.5 V )

OUT+, OUT- Voltage ................(VCCD - 1.1V) to (VCCD + 0.5V)
IN Current. $\qquad$
$\qquad$ 0 to 3 mA PDC Current. -1 mA to 0 Operating Junction Temperature Range $\left(\mathrm{T}_{\mathrm{j}}\right) \ldots . . .-55^{\circ} \mathrm{C}$ to $+125^{\circ} \mathrm{C}$ Storage Temperature Range ............................. $60^{\circ} \mathrm{C}$ to $+160^{\circ} \mathrm{C}$ Processing Temperature (Die) .$+400^{\circ} \mathrm{C}$

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

(VCCD $=\mathrm{VCCS}=+3.3 \mathrm{~V} \pm 5 \%$ or $\mathrm{VCCD}=+5.0 \mathrm{~V} \pm 10 \%, \mathrm{VCCS}=$ open, $\mathrm{T}_{\mathrm{j}}=-40^{\circ} \mathrm{C}$ to $+120^{\circ} \mathrm{C}$, unless otherwise noted. Typical values are at +3.3 V and $\mathrm{T}_{\mathrm{j}}=+25^{\circ} \mathrm{C}$.)


## AC ELECTRICAL CHARACTERISTICS

(VCCD $=\mathrm{VCCS}=+3.3 \mathrm{~V} \pm 5 \%$ or $\mathrm{VCCD}=+5.0 \mathrm{~V} \pm 10 \%$, $\mathrm{VCCS}=$ open, $\mathrm{T}_{\mathrm{j}}=-40^{\circ} \mathrm{C}$ to $+120^{\circ} \mathrm{C}$, unless otherwise noted. Typical values are at +3.3 V and $\mathrm{T}_{\mathrm{j}}=+25^{\circ} \mathrm{C}$.) (Notes 1, 2)

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Small-Signal Bandwidth | BW |  |  | 1.8 |  | GHz |
| Input Sensitivity | In | $\begin{aligned} & \text { 2.5Gbps, } 2^{23}-1 \text { PRBS, } \mathrm{BER} \leq 10^{-10} \text {, } \\ & \mathrm{CIN}=0.5 \mathrm{pF}, \mathrm{~T}_{\mathrm{j}}=+120^{\circ} \mathrm{C} \end{aligned}$ |  | 7.8 | (Note 3) | $\mu A p-p$ |
| Input-Referred RMS Noise | NIN | $\mathrm{CIN}_{\text {IN }}=0.5 \mathrm{pF}, \mathrm{T}_{\mathrm{j}}=+120^{\circ} \mathrm{C}$ |  | 433 | 566 | nA |
| Low-Frequency Cutoff | $f \mathrm{~L}$ |  |  |  | 100 | kHz |
| Power-Supply Rejection Ratio | PSRR | $\mathrm{f} \leq 2 \mathrm{MHz}, 100 \mathrm{mVp}-\mathrm{p}$ | 25 | 30 |  | dB |
| LOP Hysteresis |  | Electrical (Note 4), low LOP assert, RPD $=510 \Omega$ | 3 |  |  | dB |
| LOP Assert Level |  | RPD $=510 \Omega$ | 0.9 |  |  | $\mu \mathrm{A}$ |
| LOP Deassert Level |  | RPD $=510 \Omega$ |  |  | 8.0 | $\mu \mathrm{A}$ |
| Output Edge Speed | $\mathrm{tr}_{\mathrm{r}} \mathrm{t}$ | 20\% to 80\% (Note 5) |  | 50 | 70 | ps |
| Pulse-Width Distortion | PWD | (Notes 5, 6) |  | 21 | 80 | ps |

Note 1: $\mathrm{C}_{\mathrm{IN}}=$ total capacitance on IN.
Note 2: AC parameters are guaranteed by design and characterization.
Note 3: See Typical Operating Characteristics for worst-case distribution.
Note 4: Hysteresis = 20 log (VDEASSERT / VASSERT).
Note 5: $\mathrm{l}_{\mathrm{IN}}=2.5 \mathrm{~mA}$.
Note 6: $\mathrm{PWD}=\mid[(2 \cdot$ Pulse Width $)-$ Period $] / 2 \mid$.
Note 7: External load not required for normal operation.

# 2.5Gbps, +3.3V Combined Transimpedance/Limiting Amplifier 

Typical Operating Characteristics
$\left(\mathrm{V}_{\mathrm{CCD}}=\mathrm{V}_{\mathrm{CCS}}=+3.3 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}\right.$, unless otherwise noted. $)$

differential OUTPUT VOLTAGE
vs. TEMPERATURE


PULSE-WIDTH DISTORTION vs. INPUT CURRENT


PULSE-WIDTH DISTORTION
vs. TEMPERATURE


SUPPLY CURRENT
vs. TEMPERATURE


ELECTRICAL EYE DIAGRAM


OUTPUT COMMON-MODE VOLTAGE vs. TEMPERATURE


OUTPUT VOLTAGE vs. INPUT CURRENT


ELECTRICAL EYE DIAGRAM


### 2.5Gbps, +3.3V Combined Transimpedance/Limiting Amplifier

## Typical Operating Characteristics (continued)

$\left(\mathrm{V}_{\mathrm{CCD}}=\mathrm{V}_{\mathrm{CCS}}=+3.3 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=+25^{\circ} \mathrm{C}\right.$, unless otherwise noted.)


DISTRIBUTION OF ELECTRICAL SENSITIVITY (WORST CASE)


Pad Description

| PAD NAME | FUNCTION |
| :---: | :--- |
| VCCS | Positive Supply Voltage of Input Stage. Apply +3.3 V if VCCD $=+3.3 \mathrm{~V}$. If VCCD $>+3.47 \mathrm{~V}$, disconnect from sup- <br> ply and decouple to GND. |
| CHF+ | External Filter Capacitor. A capacitor connected between CHF+ and CHF- is used for setting the low-frequency <br> cutoff. |
| CHF- | External Filter Capacitor. A capacitor connected between CHF+ and CHF- is used for setting the low-frequency <br> cutoff. |
| FIL | On-Chip Resistor for Filtering Photodiode Supply Voltage (connected to VCCD on chip) |
| GND | Electrical Ground |
| IN+ | Signal Input |
| IN- | No Connect |
| PDC | The voltage at this node programs the gain of the power detector. Connect a resistor between PDC and INV to <br> adjust the LOP threshold. |
| INV | Used for programming the gain of the power detector. Connect a resistor between PDC and INV to adjust the <br> LOP threshold. |
| CPD- | Filter Node for Power Detector. A capacitor connected between CPD+ and CPD- will provide additional filtering <br> to the rectifier output within the power detector. |
| CPD+ | Filter Node for Power Detector. A capacitor connected between CPD+ and CPD- will provide additional filtering <br> to the rectifier output within the power detector. |
| OUT- | Inverted Data-Signal Output |
| OUT+ | Noninverted Data-Signal Output <br> LOPTTL Output, Loss-of-Power, active high <br> VCCDPower-Supply Voltage |

# 2.5Gbps, +3.3V Combined Transimpedance/Limiting Amplifier 

Typical Operating Circuits


* NOTE: IF LOP OPERATION IS NOT DESIRED, RPD $=0 \Omega$


## Circuit Description

## Data Path

The combined preamplifier and limiting postamplifier (Figure 1) accepts an input current from a photodiode attached to the input pad IN+. The transimpedance input amplifier stage converts the input current to an output voltage with a typical transimpedance of $1.4 \mathrm{k} \Omega$.
The second stage of the data path is an active highpass filter. This filter converts the single-ended input signal to a differential signal, eliminating the DC component and adding approximately 16dB of gain. The output of the highpass filter drives the power detector and limiting amplifier circuitry.
The limiting amplifier circuit is the third stage of the data signal path. It amplifies and limits the differential input signal. The output stage is a differential pair with internal $50 \Omega$ load resistors. The limited output voltage is typically $145 \mathrm{mV} p-\mathrm{p}$.

Power Detector
The power detect circuit consists of an adjustable-gain amplifier and combined rectifier with a lowpass filter. The adjustable-gain amplifier is controlled by an op amp. The gain is adjusted by means of an external resistor connected between the PDC and INV pins.

The output voltage of the adjustable gain amplifier drives the combined rectifier and lowpass filter circuitry. The resulting DC voltage is fed to a Schmitt trigger, which generates a high-level output signal if the DC input signal is below the LOP assert level, thus causing an LOP condition on the LOP output.

## Design Procedure

## Power Supply

The complete amplifier is supplied by a single supply voltage, $\mathrm{V}_{\mathrm{CCD}}$. For operation at 3.3 V , the supply voltage is applied at both the VCCD and VCCS pins (see Typical Operating Circuit). For operation at 5.0V, the voltage is only applied at VCCD. In this case, VCCS is on-chip controlled to approximately 3.2 V . In the 5.0 V configuration, an external 10 nF grounded capacitor is required at the VCCS pin.

## External Filter Capacitor CHF

The value of CHF affects the maximum speed at which the compensation loop adjusts the input offset current. ChF should be chosen between 10 nF and 100 nF . The loop should be as slow as possible to reduce patterndependent jitter. Maxim recommends a value of $\mathrm{CHF}=$ 100nF.

### 2.5Gbps, +3.3V Combined Transimpedance/Limiting Amplifier



Figure 1. Functional Diagram of the Combined Preamplifier and Limiting Postamplifier

## External Filter Capac itor CPD

The LF cutoff of the power detector can be reduced by adding external capacitance across the CPD pins. This capacitor is only needed when this circuit is operated at lower data rates and lower edge speeds. In this way, the remaining ripple of power detector output voltage is reduced.

Loss-of-Power Threshold If the LOP function is desired, Maxim recommends RPD $=510 \Omega$. If the LOP function is not desired, RPD $=0 \Omega$ (shorted). See Figure 2 for LOP definitions. If desired, the LOP threshold can be adjusted (see Assert/ Deassert vs. Rpd in the Typical Operating Characteristics.


Figure 2. Loss-of-Power Definitions with $R P D=510 \Omega$

### 2.5Gbps, +3.3V Combined Transimpedance/Limiting Amplifier

Internal Input/Output Schematics


Figure 3. OUT Pads


Figure 5. FIL Pads


Figure 4. IN Pads


Figure 6. CHF Pads

### 2.5Gbps, +3.3V Combined <br> Transimpedance/Limiting Amplifier

MAX3866 $\qquad$ Internal Input/Output Schematics (continued)


Figure 7. INV Pad


Figure 9. LOP Pad


Figure 8. PDC Pad


Figure 10. CPD Pad

### 2.5Gbps, +3.3V Combined Transimpedance/Limiting Amplifier

## Applic ations Information

## Converting Average Optical Power to Signal Amplitude

Many of the MAX3866's specifications relate to input signal amplitude. When working with fiber optic receivers, the input is usually expressed in terms of average optical power and extinction ratio. The relations given in Table 1 are helpful for converting optical power to input signal when designing with the MAX3866.
In an optical receiver, the input current to the transimpedance amplifier can be found by multiplying the power relationships in Table 1 with the photodiode responsivity.

## Wire Bonding

Make corrections to the die with gold wire only, using ball bonding techniques. Die pad size is $4 \mathrm{mils}(100 \mu \mathrm{~m})$ square and die thickness is 12mils ( $\sim 300 \mu \mathrm{~m}$ ).

## Layout Techniques

The MAX3866's performance can be greatly affected by circuit board layout and design. Use good high-frequency design techniques, including minimizing ground inductances and using fixed-impedance transmission lines on all data signals.

Table 1. Optical-Power Relations*

| PARAMETER | SYMBOL | RELATION |
| :---: | :---: | :---: |
| Average Power | Pave | PAVE $=(P 0+P 1) / 2$ |
| Extinction Ratio | $\mathrm{re}_{\mathrm{e}}$ | $\mathrm{r}_{\mathrm{e}}=\mathrm{P} 1 / \mathrm{P} 0$ |
| Optical Power of a " 1 " | P1 | $\mathrm{P} 1=2 \mathrm{P}_{\mathrm{AVE}} \frac{r_{\mathrm{e}}}{\mathrm{r}_{\mathrm{e}}+1}$ |
| Optical Power of a " 0 " | P0 | $\mathrm{PO}=2 \mathrm{PaVE}^{\text {A }} /\left(\mathrm{re}_{\mathrm{e}}+1\right)$ |
| Signal Amplitude | PIN | $\mathrm{P}_{\mathrm{IN}}=\mathrm{P}_{1}-\mathrm{P} 0=2 \mathrm{P}_{\mathrm{AVE}} \frac{\left(\mathrm{r}_{\mathrm{e}}-1\right)}{\left(\mathrm{r}_{\mathrm{e}}+1\right)}$ |

*Assuming a 50\% average input mark density.

Pad Configuration


TRANSISTOR COUNT: 851
2.5Gbps, +3.3V Combined Transimpedance/Limiting Amplifier

### 2.5Gbps, +3.3V Combined Transimpedance/Limiting Amplifier

NOTES

# 2.5Gbps, +3.3V Combined Transimpedance/Limiting Amplifier 

## NOTES

